

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHUNPEI YAMAZAKI	09/21/2010
JUNICHIRO SAKATA	09/30/2010
KOSEI NODA	09/30/2010
MASAYUKI SAKAKURA	09/23/2010
YOSHIAKI OIKAWA	09/30/2010
HOTAKA MARUYAMA	09/23/2010
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
<b>Street Address:</b>	398, HASE
<b>City:</b>	ATSUGI-SHI, KANAGAWA-KEN
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	243-0036
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13870027
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(877)769-7945
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<b>ATTORNEY DOCKET NUMBER:</b>	12732-0682002
<b>NAME OF SUBMITTER:</b>	JANELLE A. JACKSON
<b>SIGNATURE:</b>	/Janelle A. Jackson/
<b>DATE SIGNED:</b>	10/22/2014
<b>Total Attachments: 2</b>	

PATENT

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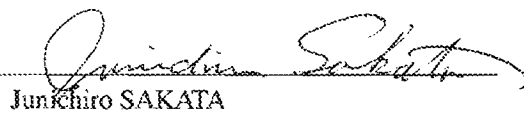
ASSIGNMENT

For valuable consideration, We, Shunpei YAMAZAKI of Setagaya, Tokyo, Japan, Junichiro SAKATA of Atsugi, Kanagawa, Japan, Kosei NODA of Atsugi, Kanagawa, Japan, Masayuki SAKAKURA of Tochigi, Tochigi, Japan, Yoshiaki OIKAWA of Sagamihara, Kanagawa, Japan and Hotaka MARUYAMA of Tochigi, Tochigi, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME, filed 4/25/2013, and assigned U.S. Serial Number 13/870,027, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature   
Name: Shunpei YAMAZAKI  
Date: 09/21/2010

Signature   
Name: Junichiro SAKATA  
Date: 09/30/2010

Signature Kosei Noda  
Name: Kosei NODA  
Date: 09/30/2010

Signature Masayuki Sakakura  
Name: Masayuki SAKAKURA  
Date: 09/23/2010

Signature Yoshiaki Oikawa  
Name: Yoshiaki OIKAWA  
Date: 09/30/2010

Signature Hotaka Maruyama  
Name: Hotaka MARUYAMA  
Date: 09/23/2010